

## Attorney Docket No: 0492611-0545/MIT-9277CONII IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Seleznev, et al.

Examiner:

Cooke

Serial No.:

10/799,388

Art Unit:

1754

Filing Date:

March 12, 2004

VACUUM PROCESSING FOR FABRICATION OF

Title:

SUPERCONDUCTING THIN FILMS FABRICATED BY METAL-

ORGANIC PROCESSING

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

#### **CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P. O. Box 1450, Alexandria, VA 22313-1450, on June 3, 2005.

Susan M. Dinsmore

# STATEMENT FILED PURSUANT TO THE DUTY OF DISCLOSURE UNDER 37 CFR §§1.56, 1.97 AND 1.98

Pursuant to the duty of disclosure under 37 C.F.R. §§1.56, 1.97 and 1.98, Applicants respectfully request consideration of this Information Disclosure Statement.

### PART I: Compliance with 37 C.F.R. §1.97

(Select A, B or C below)

A.	[]	This Information Disclosure Statement has been filed:				
		(chec	ck 1, 2 and/or 3 below)			
	1.	[]	within three months of the filing date of the above identified U.S. Patent			
			application;			
	2.	[]	within three months of the filing date of the entry of the National Stage, as			
			set forth in 37 C.F.R. §1.491, in an International application; and/or			

Page 1 of 5

Attorney Docket No.: 0492611-0545

06/06/2005 SFELEKE1 00000008 10799388 180.00

	3.	IJ		e-identified application.				
		No fe		rtification is required.				
B.	[X]			ation Disclosure Statement has been filed more than three months				
		after	the filir	ng date of the present application and after the mailing date of this				
		first (	Office A	Action, but before the mailing date of either a final action under 37				
		C.F.R	R. §1.11	3 or a Notice of Allowance under 37 C.F.R. §1.311.				
		(chec	k 1 or 2	2 below)				
	1.	[X]	The f	fee of \$180 as set forth in 37 C.F.R. §1.17(p) is enclosed; or				
	2.	[]	Appl	icants hereby certify, as specified in 37 C.F.R. §1.97(e), that				
			(chec	ck a or b below)				
		a.	[]	each item of information contained in this Information Disclosure				
				Statement was cited in a communication from a foreign Patent				
				Office in a counterpart for this application not more than three				
				months prior to the filing of this Statement; or				
		b.	[]	no item of information contained in this Information Disclosure				
				Statement was cited in a communication from a foreign Patent				
				Office in a counterpart for this application or, to the knowledge of				
				the undersigned after making reasonable inquiry, was known to				
				any individual designated in 37 C.F.R. §1.56(c) more than three				
				months prior to the filing of this Statement.				
		c.	[]	items indicated by an asterisk were identified in a recent review of				
				related files.				
C.	[]	This 1	Informa	ation Disclosure Statement has been filed after the mailing date of				
		either	a Fina	l action under 37 C.F.R. §1.113 or a Notice of Allowance under 37				
		C.F.R	k. §1.31	1 and before payment of an Issue Fee.				
		(chec	(check 1, 2, and 3 below)					
	1.	[]	The	Applicant hereby certifies, as specified in 37 C.F.R. §1.97(e), that:				
			(chec	ck a or b below)				

		a.	[]	each item of information contained in this Information Disclosure
				Statement was cited in a communication from a foreign Patent
				Office in a counterpart for this application not more than three
				months prior to the filing of this Statement.
		b.	[]	no item of information contained in this Information Disclosure
				Statement was cited in a communication from a foreign Patent
				Office in a counterpart for this application or, to the knowledge of
				the undersigned after making reasonable inquiry, was known to
				any individual designated in 37 C.F.R. §1.56(c) more than three
				months prior to the filing of this Statement.
	2.	[]	A Pet	ition requesting consideration of the Information Disclosure
			Stater	ment is attached.
	3.	[]	The P	Petition Fee of \$130 as set forth in 37 C.F.R. §1.17(i)(1) is enclosed.
PAR7	<u>Γ II - Inf</u>	ormatic	on Cited	<u>1</u>
A.	[X]	The A	Applicar	nt hereby makes of record in the above-identified application the
		refere	ence(s) l	isted on the attached form PTO-1449 (modified). The order of
		prese	ntation	of the references should not be construed as an indication of the
		impo	rtance o	f the references.
B.	[]	The A	Applicar	nt hereby makes the following additional information of record in the
		above	e-identif	fied application:
				•
PAR7	ГШ: Е:	xplanat	ion of N	Non-English Language References and Remarks Concerning Other
<u>Inforr</u>	nation (			
A.	[]			g is a concise explanation of the relevance of each non-English
		langu	age refe	erence listed on the attached form PTO-1449 (modified):
B.	[]	The f	ollowin	g are remarks concerning the other information cited:

### PART IV: Remarks

- A. [X] Copies of references (check 1 or 2 below)
  - 1. [X] A copy of each of the references cited on the attached form PTO-1449 (modified) is enclosed, except for U.S. patents and U.S. patent application publications for which the submission requirement has been waived by the PTO in the Official Gazette Notice of August 5, 2003, for applications filed after June 30, 2003.
  - 2. [X] Copies of certain of the references cited on the attached form PTO-1449 (modified) are not enclosed because each of these references (indicated by asterisk) was previously cited by or submitted to the Office in a prior application, U.S.S.N. 10/194,561, which prior application is relied upon for an earlier filing date under 35 U.S.C. § 120.
- B. [X] It is respectfully requested that: (check 1, 2, and 3 below)
  - 1. [X] The Examiner consider completely the cited information, along with any other information, in reaching a determination concerning the patentability of the present claims;
  - 2. [X] The enclosed form PTO-1449 be signed by the Examiner to evidence that the cited patent(s) and publication(s) has (have) been fully considered by the Patent and Trademark Office during the examination of this application;
  - 3. [X] The citations for the patent(s) and publication(s) be printed on any patent which issues from this application.
- C. [X] By submitting this Information Disclosure Statement, Applicants make no representation that a search has been performed, of the extent of any search performed, or that more material information may not exist.

- D. [X] By submitting this Information Disclosure Statement, Applicants make no representation that the information cited in the Statement is, or is considered to be, material to patentability as defined in 37 C.F.R. §1.56(b).
- E. [X] By submitting this Information Disclosure Statement, Applicants make no representation that the information cited in the Statement is, or is considered to be, in fact, prior art as defined by 35 U.S.C. §102.
- F. [X] Notwithstanding any statements by Applicants, the Examiner is urged to form his or her own conclusions regarding the relevance of the cited reference(s).

An early and favorable action is hereby requested.

Please charge any additional fees or credit any overpayments to our Deposit Account No. 03-1721.

Respectfully submitted,

Valarie B. Rosen, Ph.D.

Registration Number 45,698

CHOATE, HALL & STEWART, LLP Exchange Place 53 State Street Boston, Massachusetts 02109 (617) 248-5000

Dated: June 3, 2005

Form PTO-144 (REV. 8-83)	w ne 2005 Comme	epartment of erce and Trademark Office	Atty. Docket: 0492611-0545/MIT- 9277CONII	In re Application No. 10/799,388	
(KE v. 6-63)	i atont	and Trademark Office	Applicant: Seleznev, et al.		
	SUDISCLOSURE S'		Filing Date:	Group:	
(Use seve	eral sheets if necessar	y) 	March 12, 2004	1754	
U.S. PATENT I	DOCUMENTS				
Examiner's	U.S. Patent No.	Applicant	Issue Date	Class	Subclass
Initials	4,931,425	Kimura, et al.	June, 1990		
				505	1
	4,959,346	Mogro-Campero,	September 25, 1990	505	1
		et al.			
	5,143,898	Takano, et al.	September 1, 1992	505	1
	5,225,561	Kirlin, et al.	July, 1993		
	5,231,074	Cima, et al.	July 27, 1993	505	1
	5,280,012	Kirlin, et al.	January, 1994		
	5,296,460	Wessels, et al.	March, 1994		
	5,306,698	Ahn, et al.	April 26, 1994	505	475
	5,308,800	Wehrle, et al.	May 3, 1994	505	400
	5,319,118	Norman, et al.	June, 1994		
	5,453,494	Kirlin, et al.	September, 1995		
	5,603,983	Clough, et al.	February, 1997		
	5,661,114	Otto, et al.	August 26, 1997	505	501
	5,741,377	Goyal, et al.	April 21, 1998	148	512
	5,850,098	Butler, et al.	December 15, 1998	257	467
	5,854,587	Horwitz, et al.	December 29, 1998	338	22
	5,856,277	Chen, et al.	January 5, 1999	505	452
	5,972,847	Feenstra, et al.	October 26, 1999	505	473
<del></del>	6,172,009	Smith, et al.	January 9, 2001	505	473
	6,486,100	Lee, et al.	November 26, 2002	505	470
	6,673,387	Zhang, et al.	January 6, 2004	427	62
U.S. PATENT	APPLICATIONS				
Examiner's Initials:	Serial Number:	Applicant:	Filing Date:	Group:	Art Unit:
	2002/0182451	Smith, et al.	December 5, 2002		

Form PTO-1449 (REV. 8-83)	Comm	Department of nerce and Trademark Office	Atty. Docket: In re Application 10/799,388 9277CONII		_		
			Applicant: Seleznev, et al.				
	DISCLOSURE S		Filing Date:	Group:			
(Use sever	ral sheets if necesso	ıry)	March 12, 2004	1754			
	2003/0050195	Wiesmann, et al.	March 13, 2003				
	2005/0014052	Seleznev, et al.	January 20, 2005				
FOREIGN PATI	ENT DOCUMEN	ΓS	A				
Examiner's	Document No.	Country	Date	Translat	ion		
Initials	2004			Yes	No		
	WO 96/32201	PCT	October 17, 1996				
OTHER DOCUM	MENTS						
Examiner's Initials	<b>,</b>	ng Author, Title, Date, Po "Increased Transition To		evaporated YB	a₂Cu₃O <sub>7-δ</sub>		
	Berkowitz, et al., "Increased Transition Temperature in in situ Coevaporated YBa <sub>2</sub> Cu <sub>3</sub> O <sub>7-8</sub> Thin Films by Low Temperature Post-annealing", Appl. Phys. Lett. 65 1587-1589 (1994)  Chan, et al., "Effect of the post-Deposition Processing Ambient on the Preparation of Superconducting YBa <sub>2</sub> Cu <sub>3</sub> O <sub>7-x</sub> Coevaporated Thin Films Using a BaF <sub>2</sub> Source", Appl. Phy. Lett. 53 1443-1445 (1988)  *Cima, et al., "Conversion Kinetics of Oxyfluoride-Derived YBCO Films", Materials Research Society Fall Conference, November 28-December 3, 1999  de Obaldia, et al., "Coexistence of Grains With Differing Orthorhombicity in High Quality YBa <sub>2</sub> Cu <sub>3</sub> O <sub>7-8</sub> Thin Films", Appl. Phys. Lett. 65 3395-3397 (1994)  DeSantolo, et al., "Preparation of High T <sub>c</sub> and J <sub>c</sub> Films of Ba <sub>2</sub> YCu <sub>3</sub> O <sub>7</sub> Using Laser Evapor of a Composite Target Containing BaF <sub>2"</sub> , Appl. Phys. Lett. 52 1995-1997 (1988)  Feenstra, et al., "Effect of Oxygen Pressure on the Synthesis of YBa <sub>2</sub> Cu <sub>3</sub> O <sub>7-x</sub> Thin Films b Post-Deposition Annealing", J. Appl. Phys. 69 6569-6585 (1991)  Foltyn, et al., "Pulsed Laser Deposition of Thick YBa <sub>2</sub> Cu <sub>3</sub> O <sub>7-8</sub> Films With Jc>1 MA/cm <sup>2</sup> " Appl. Phys. Lett. 63 1848-1850 (1993)  Gupta, et al., "Superconducting Oxide Films with High Transition Temperature Prepared Metal Trifluoroacetate Precursors", Appl. Phys. Lett. 52 2077-2079 (1988)  He, et al., "Deposition of Biaxially-Oriented Metal and Oxide Buffer-Layer Films on Text Ni Tapes: New Substrates for High-Current, High-Temperature Superconductors", Physica 275 155-161 (1997)  Juang, et al., "Enhancement of Critical Current Density in Direct-Current-Sputtered TiBa <sub>2</sub> Ca <sub>2</sub> Cu <sub>3</sub> O <sub>9+8</sub> Superconducting Thin Films", Appl. Phys. Lett. 66 885-887 (1995)  Krause, Carolyn, "Hot Wire: ORNL's Promising Route to Superconductivity", Oak Ridge National Laboratory Review 29 2-7 (1996)  Mankiewich, et al., "High Critical-Current Density Ba <sub>2</sub> YCu <sub>3</sub> O <sub>7</sub> Thin Films Produced by						
	Coevaporation of Y <sub>1</sub> Cu <sub>1</sub> and BaF <sub>2</sub> ", High Temperature Superconductivity 1 18a-18g (1986-1988)  Mankiewich, et al., "Preparation and Processing of Thin Film Ba <sub>2</sub> YCu <sub>3</sub> O <sub>7</sub> ", High Temperature Superconductivity 1 17a-17q (1986-1988)  Mankiewich, et al., "Reproducible Technique for Fabrication of Thin Films of High Transition Temperature Superconductors", High Temperature Superconductivity 1 19a-19c (1986-1988)						

Form PTO-1449	U.S. Department of Commerce	Atty. Docket: 0492611-0545/MIT-	In re Application No. 10/799,388		
(REV. 8-83)	Patent and Trademark Office	9277CONII  Applicant: Seleznev, et al.			
	I DISCLOSURE STATEMENT al sheets if necessary)	Filing Date: March 12, 2004	Group: 1754		
	McIntyre, et al., "Effect of Growth Condit Chemically Derived Epitaxial Thin Films 1868-1877 (1992)				
		d Growth of Chemically Derived Ba <sub>2</sub> YCu <sub>3</sub> O <sub>7-x</sub> Thin 5263-5272 (1995)			
	McIntyre, et al., "The Effects of Substrate Ba <sub>2</sub> YCu <sub>3</sub> O <sub>7-x</sub> Thin Films on (001) LaAlO <sub>3</sub>	Surface Steps on the Micros	: [1] - [1]		
	Superconducting Tapes with High Critical	Biaxially Textured Nickel (001): An Approach to al Current Density", Science 274 755-757 (1996)			
:	Roas, et al., Epitaxial Growth of YBa <sub>2</sub> Cu <sub>3</sub> Appl. Phys. Lett. 53 1557-1559 (1988)				
	*Seleznev, et al., "Conversion Kinetics of Oxyfluoride-Derived YBCO Films", Materials Research Society Fall Conference, November 27-December 1, 2000  Skofronick, et al., "Orientation of YBa <sub>2</sub> Cu <sub>3</sub> O <sub>7-x</sub> Films on Unbuffered and CeO <sub>2</sub> -Buffered Yttria-Stabilized Zirconia Substrates", J. Appl. Phys. 76 4753-4760 (1994)				
	*Smith, et al., "High Critical Current Density Thick MOD-Derived YBCO Films", IEEE Transactions on Applied Superconductivity, 9 1531-1534 (1999)  *Solovyov, et al., "Ex-Situ Post-Deposition Processing for Large Area Y <sub>1</sub> Ba <sub>2</sub> Cu <sub>3</sub> O <sub>7</sub> Films Coated Tapes", IEEE Transactions on Applied Superconductivity 11 2939-2942 (2001)				
	*Solovyov, et al., "Growth Rate Limiting Mechanisms of Y <sub>1</sub> Ba <sub>2</sub> Cu <sub>3</sub> O <sub>7</sub> Films Manufa Ex Situ Processing", <i>Physica C</i> <b>353</b> 14-22 (2001)				
	Suenaga, "Growth Kinetics and Microstru U.S. Department of Energy, Superconduct 2000				
	Suenaga, et al., "Practical Conductor Devel High T <sub>c</sub> Oxides", Brookhaven National La				
	Suenaga, et al., "Superconductivity for Ele Superconductivity program for Electrical National Laboratory Peer Review, July 17	Systems, 2000 Annual Peer I -19, 2000	Review, Brookhaven		
	Tanaka, et al., High-J <sub>c</sub> Superconducting Single Crystalline HoBaCuO Thin Films by Sputtering", <i>Jpn. J. Appl. Phys.</i> 27 L622-L624 (1988)				
	U.S. Department of Energy's Superconductive Peer Review, July 31 and August 1, 1996				
	U.S. Department of Energy's 1997 Wire D Wu, et al., "Preparation of High Quality Y				
	Substrates with Textured Buffer Layers", 2001-2006 (1995)	IEEE Transactions on Applie	ed Superconductivity 5		
	Yee, et al., "Critical Current and Texture Institute of Physics, Conference Proceeding of High Temperature Superconductors, Ha 140 (1988)	igs 165 Thin Film Processing	g and Characterization		

Form PTO-1449 (REV. 8-83)	U.S. Department of Commerce Patent and Trademark Office	Atty. Docket: 0492611-0545/MIT- 9277CONII	In re Application No. 10/799,388		
INFORMATION DIS	CLOSURE STATEMENT	Applicant: Seleznev, et al.			
	ets if necessary)	Filing Date: March 12, 2004	Group: 1754		
Young, et al., "Superconductivity in the Fluorinated YBaCuO", Mat. Res. Soc. Symp. Proc. 99 549-552 (1988)					

3933227v1